

General Description

The WST3035 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WST3035 meet the RoHS and Green Product requirement , with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

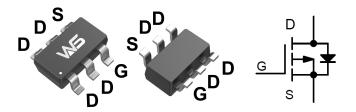
Product Summery

BVDSS	RDSON	ID
-30V	50mΩ	-4.4A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT- 23-6L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	-30	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -4.5V ¹	А		
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.0	А	
I _{DM}	Pulsed Drain Current ²	-14	Α	
P _D @T _A =25°C	Total Power Dissipation ³ 1		W	
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$ C	
T_J	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		125	°C/W	
R _{eJC}	Thermal Resistance Junction-Case ¹		80	°C/W	



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.014		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-3A		50	60	mΩ
$R_{DS(ON)}$		V _{GS} =-4.5V , I _D =-2A		73	90	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-0.5	-1.0	-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} , I _D =-250uA		3.95		mV/℃
l	Drain Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25℃			-1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =55℃			-5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V_{DS} =-5V , I_D =-3A		12.8		S
Qg	Total Gate Charge (-4.5V)			12	14.3	
Q_{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-3A		1.92	2.6	nC
Q_{gd}	Gate-Drain Charge			3.3	4.3	
$T_{d(on)}$	Turn-On Delay Time			5.9	11.2	
T _r	Rise Time	V _{DD} =-15V ,		42	73	no
$T_{d(off)}$	Turn-Off Delay Time	V_{GS} =-4.5V , R_{G} =3.3 Ω ,		34	67	ns
T _f	Fall Time	I _D =-3A		19	36	
C _{iss}	Input Capacitance			895	1200	
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		134	160	pF
C _{rss}	Reverse Transfer Capacitance			120	151	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}	V =V =0V Force Current			-1	Α
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			-14	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}$ C			-1	V
t _{rr}	Reverse Recovery Time			23		nS
Q _{rr}	Reverse Recovery Charge	lF=-3A , dl/dt=100A/µs , T _J =25℃		7.2		nC

Note

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The power dissipation is limited by 150 $^{\circ}\mathrm{C}^{\circ}$ junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

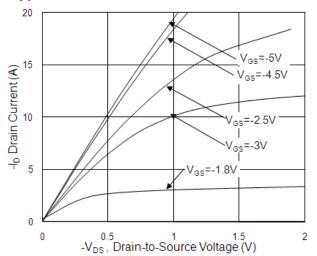


Fig.1 Typical Output Characteristics

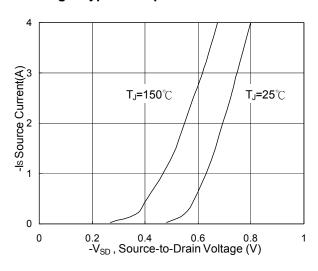


Fig.3 Forward Characteristics of Reverse

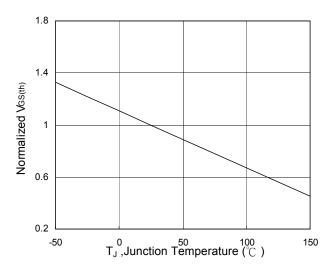


Fig.5 Normalized V_{GS(th)} vs. T_J

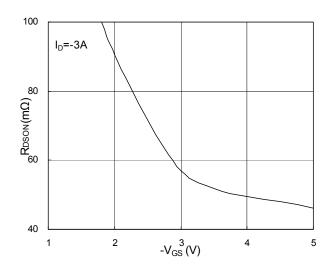


Fig.2 On-Resistance vs. G-S Voltage

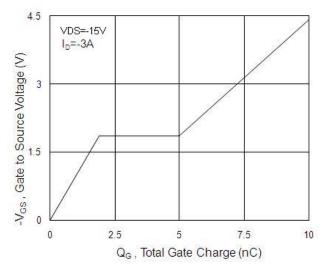


Fig.4 Gate-charge Characteristics

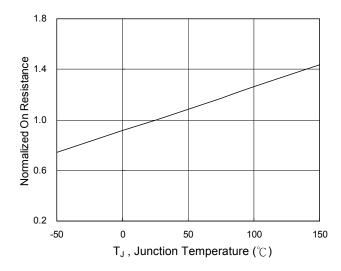
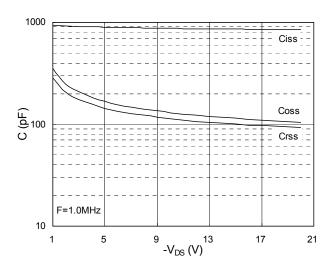


Fig.6 Normalized R_{DSON} vs. T_J





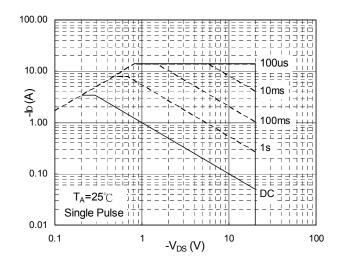


Fig.7 Capacitance

Fig.8 Safe Operating Area

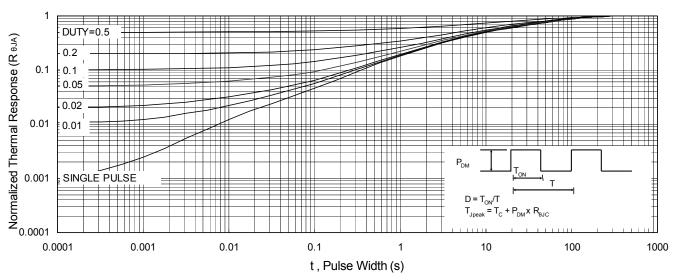
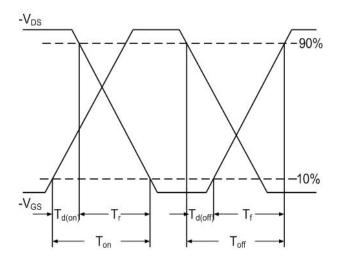


Fig.9 Normalized Maximum Transient Thermal Impedance



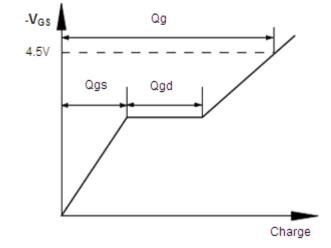


Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform



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